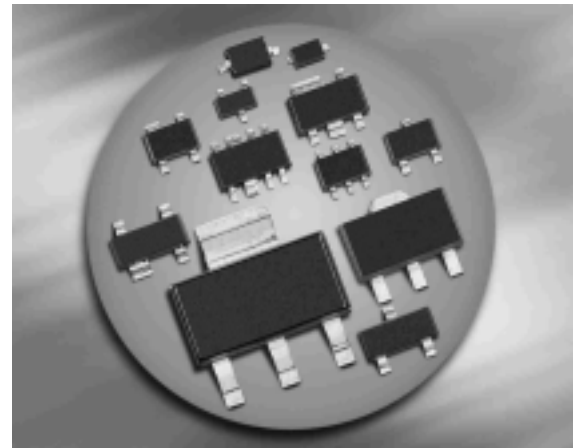
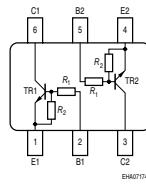
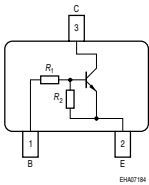


NPN Silicon Digital Transistor

- Switching in circuit, inverter, interface circuit, drive circuit
- Built in bias resistor ($R_1 = 10\text{ k}\Omega$, $R_2 = 10\text{ k}\Omega$)
- BCR133S: Two internally isolated transistors with good matching in one multichip package
- BCR133S: For orientation in reel see package information below


**BCR133/F/L3
BCR133T/W**


Type	Marking	Pin Configuration						Package
BCR133	WCs	1=B	2=E	3=C	-	-	-	SOT23
BCR133F	WCs	1=B	2=E	3=C	-	-	-	TSFP-3
BCR133L3	WC	1=B	2=E	3=C	-	-	-	TSLP-3-4
BCR133S	WCs	1=E1	2=B1	3=C2	4=E2	5=B2	6=C1	SOT363
BCR133T	WC	1=B	2=E	3=C	-	-	-	SC75
BCR133W	WCs	1=B	2=E	3=C	-	-	-	SOT323

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CEO}	50	V
Collector-base voltage	V_{CBO}	50	
Input forward voltage	$V_{i(fwd)}$	40	
Input reverse voltage	$V_{i(rev)}$	10	
Collector current	I_C	100	mA
Total power dissipation- BCR133, $T_S \leq 102^\circ\text{C}$ BCR133F, $T_S \leq 128^\circ\text{C}$ BCR133L3, $T_S \leq 135^\circ\text{C}$ BCR133S, $T_S \leq 115^\circ\text{C}$ BCR133T, $T_S \leq 109^\circ\text{C}$ BCR133W, $T_S \leq 124^\circ\text{C}$	P_{tot}	200 250 250 250 250 250	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-65 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}		K/W
BCR133		≤ 240	
BCR133F		≤ 90	
BCR133L3		≤ 60	
BCR133S		≤ 140	
BCR133T		≤ 165	
BCR133W		≤ 105	

¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

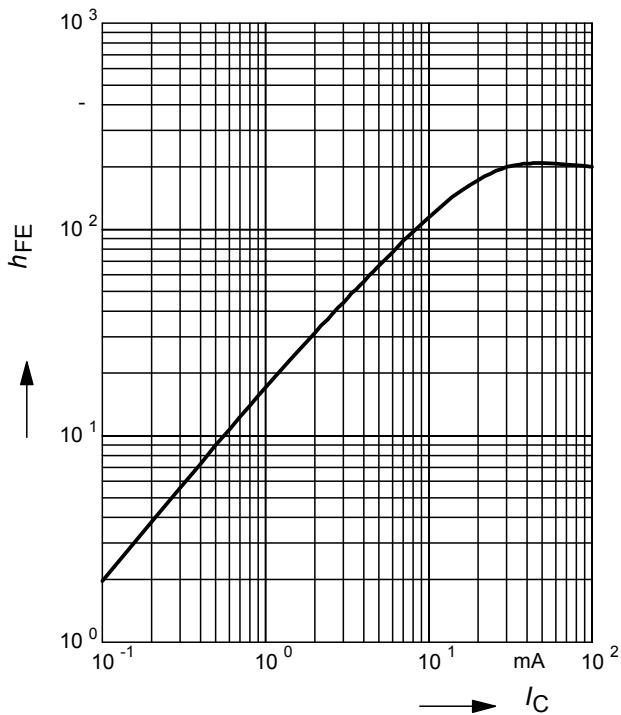
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 100 \mu\text{A}, I_B = 0$	$V_{(BR)CEO}$	50	-	-	V
Collector-base breakdown voltage $I_C = 10 \mu\text{A}, I_E = 0$	$V_{(BR)CBO}$	50	-	-	
Collector-base cutoff current $V_{CB} = 40 \text{ V}, I_E = 0$	I_{CBO}	-	-	100	nA
Emitter-base cutoff current $V_{EB} = 10 \text{ V}, I_C = 0$	I_{EBO}	-	-	0.75	mA
DC current gain ¹⁾ $I_C = 5 \text{ mA}, V_{CE} = 5 \text{ V}$	h_{FE}	30	-	-	-
Collector-emitter saturation voltage ¹⁾ $I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$	V_{CEsat}	-	-	0.3	V
Input off voltage $I_C = 100 \mu\text{A}, V_{CE} = 5 \text{ V}$	$V_{i(off)}$	0.8	-	1.5	
Input on voltage $I_C = 2 \text{ mA}, V_{CE} = 0.3 \text{ V}$	$V_{i(on)}$	1	-	2.5	
Input resistor	R_1	7	10	13	k Ω
Resistor ratio	R_1/R_2	0.9	1	1.1	-
AC Characteristics					
Transition frequency $I_C = 10 \text{ mA}, V_{CE} = 5 \text{ V}, f = 100 \text{ MHz}$	f_T	-	130	-	MHz
Collector-base capacitance $V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$	C_{cb}	-	3	-	pF

¹Pulse test: $t < 300 \mu\text{s}$; $D < 2\%$

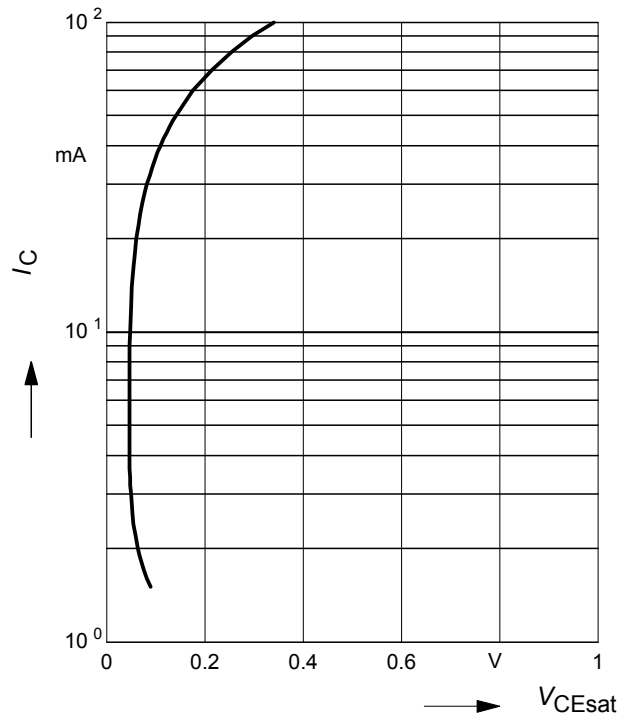
DC current gain $h_{FE} = f(I_C)$

$V_{CE} = 5\text{ V}$ (common emitter configuration)



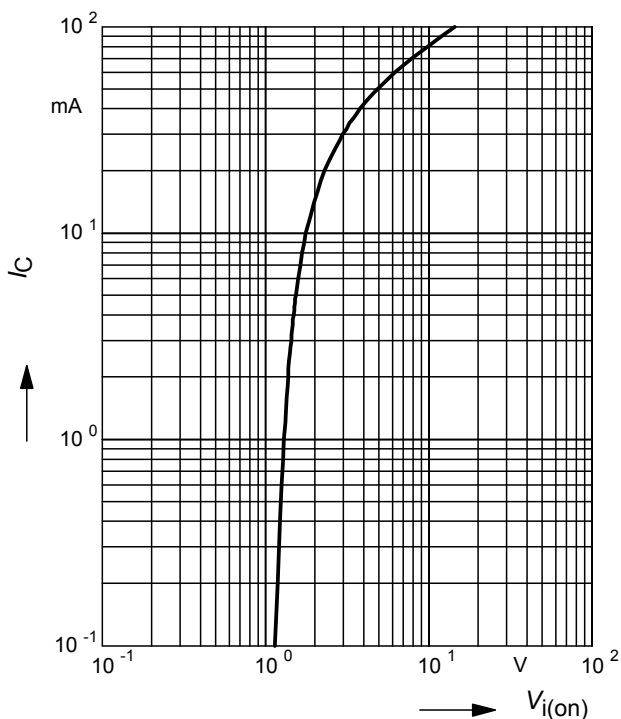
Collector-emitter saturation voltage

$V_{CEsat} = f(I_C), h_{FE} = 20$



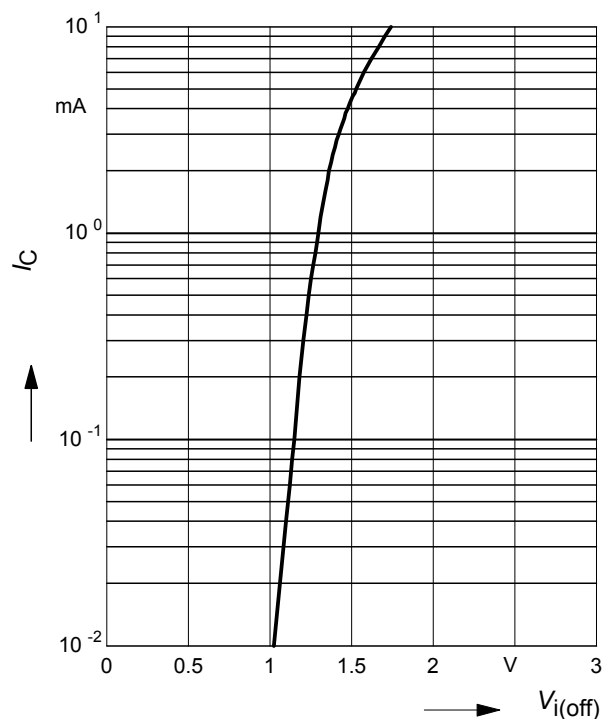
Input on Voltage $V_{i(on)} = f(I_C)$

$V_{CE} = 0.3\text{ V}$ (common emitter configuration)



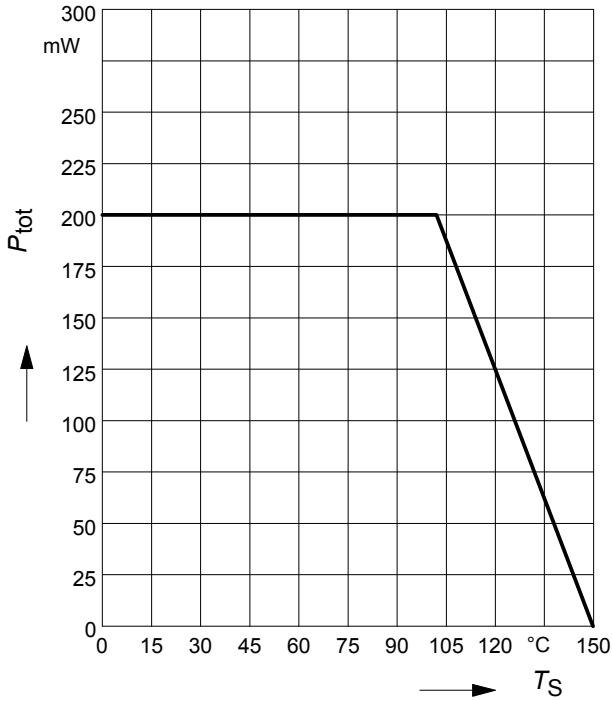
Input off voltage $V_{i(off)} = f(I_C)$

$V_{CE} = 5\text{ V}$ (common emitter configuration)



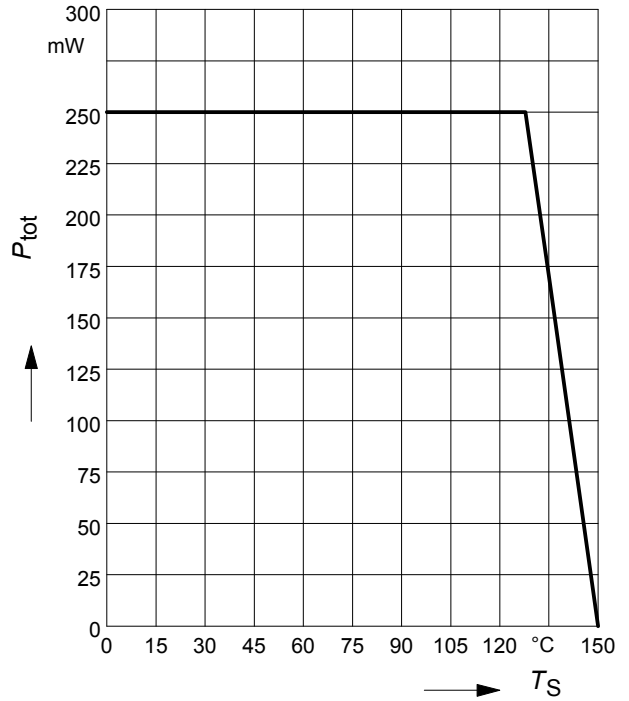
Total power dissipation $P_{tot} = f(T_S)$

BCR133



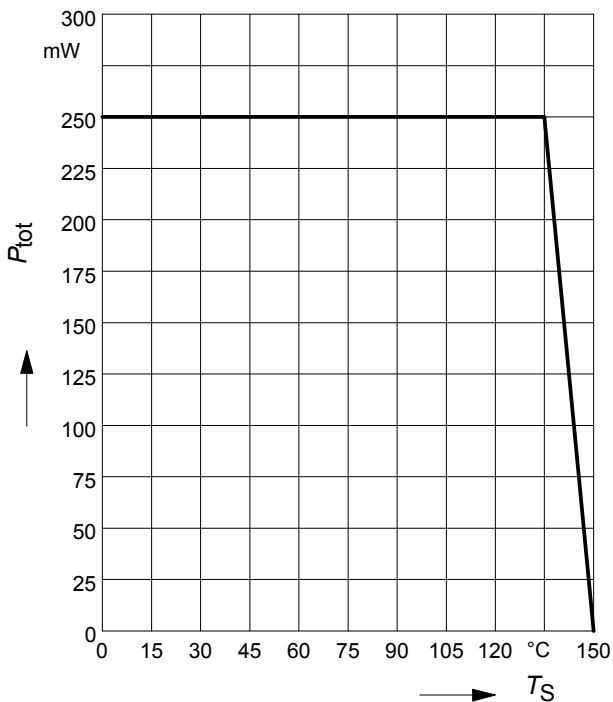
Total power dissipation $P_{tot} = f(T_S)$

BCR133F



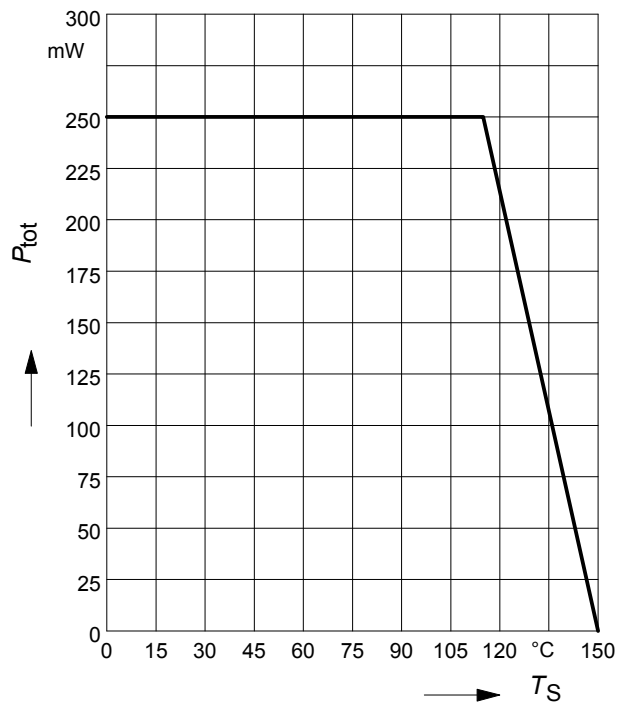
Total power dissipation $P_{tot} = f(T_S)$

BCR133L3



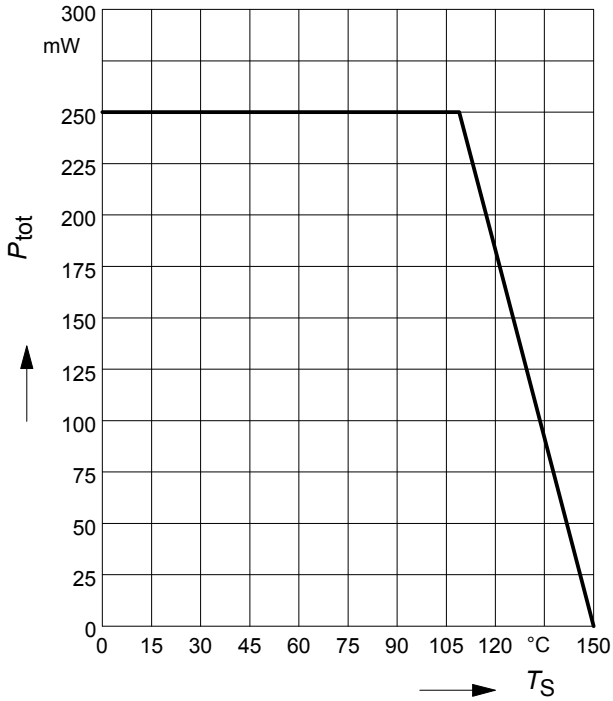
Total power dissipation $P_{tot} = f(T_S)$

BCR133S



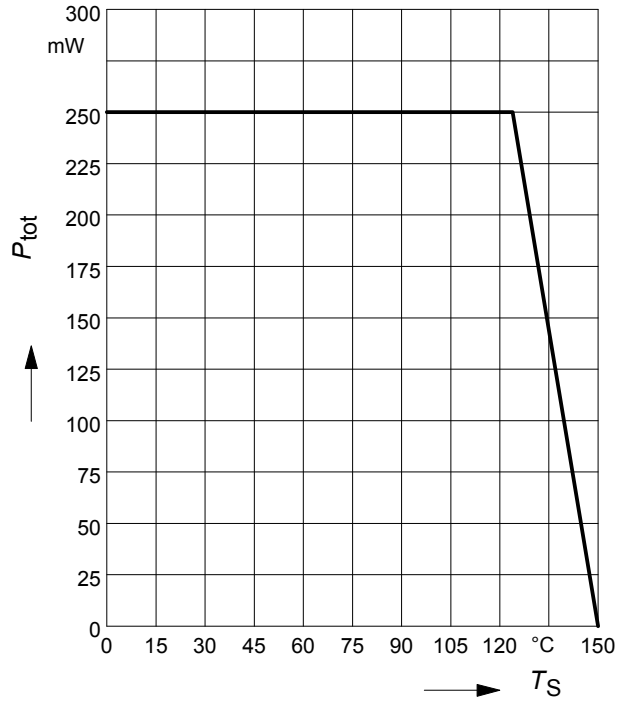
Total power dissipation $P_{tot} = f(T_S)$

BCR133T



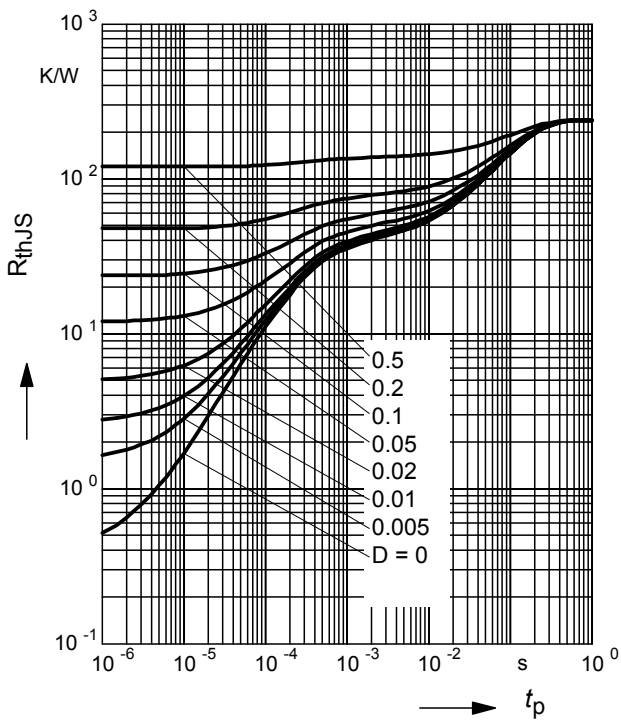
Total power dissipation $P_{tot} = f(T_S)$

BCR133W



Permissible Pulse Load $R_{thJS} = f(t_p)$

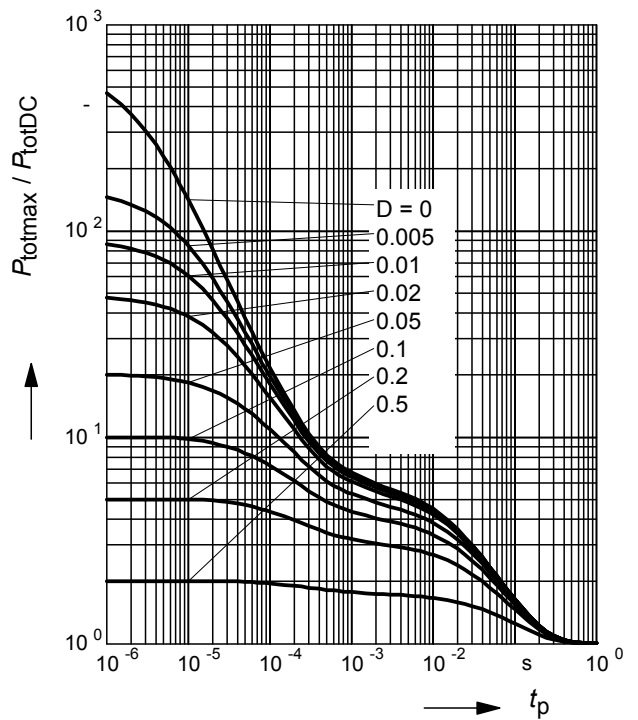
BCR133



Permissible Pulse Load

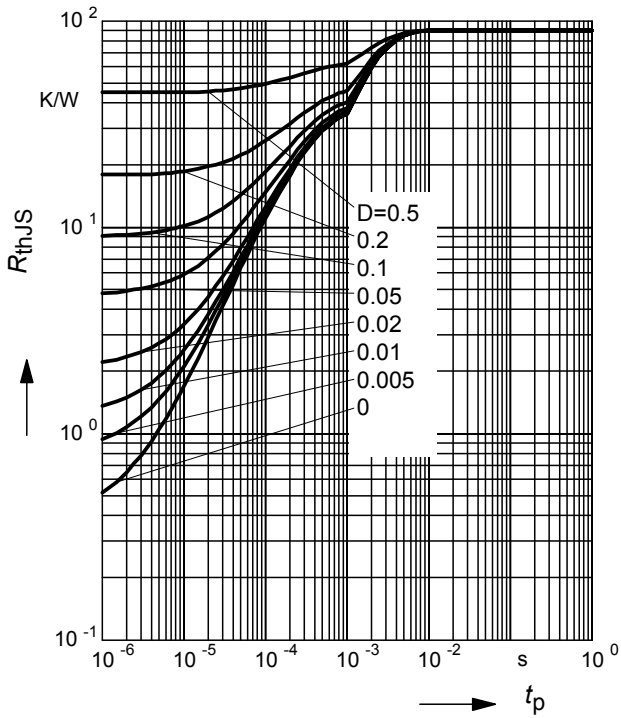
$P_{totmax}/P_{totDC} = f(t_p)$

BCR133



Permissible Puls Load $R_{thJS} = f(t_p)$

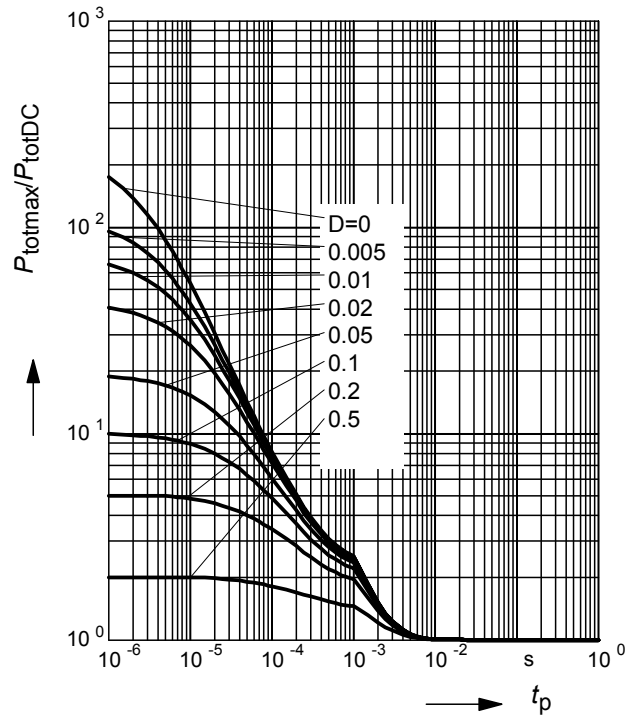
BCR133F



Permissible Pulse Load

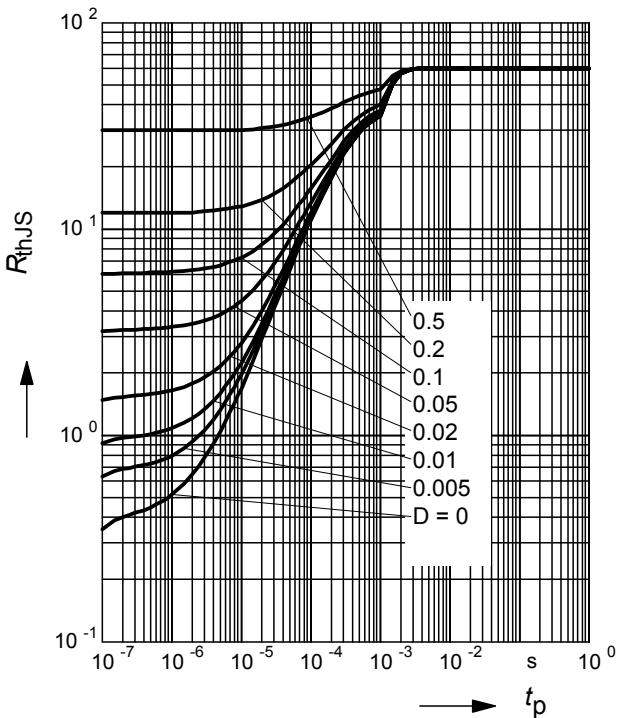
$P_{totmax}/P_{totDC} = f(t_p)$

BCR133F



Permissible Puls Load $R_{thJS} = f(t_p)$

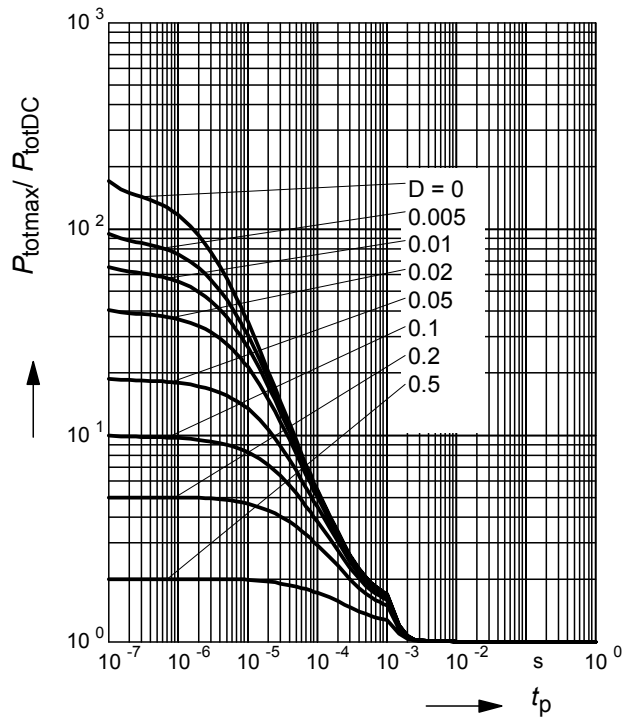
BCR133L3



Permissible Pulse Load

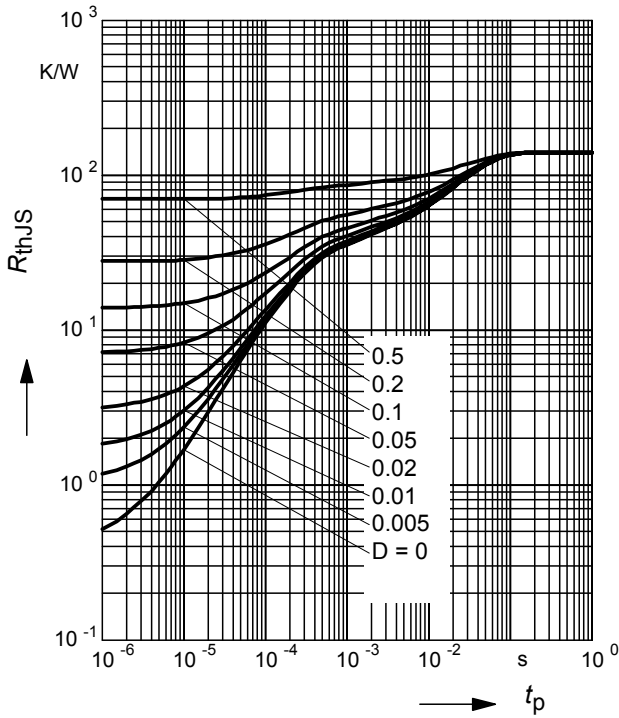
$P_{totmax}/P_{totDC} = f(t_p)$

BCR133L3



Permissible Puls Load $R_{thJS} = f(t_p)$

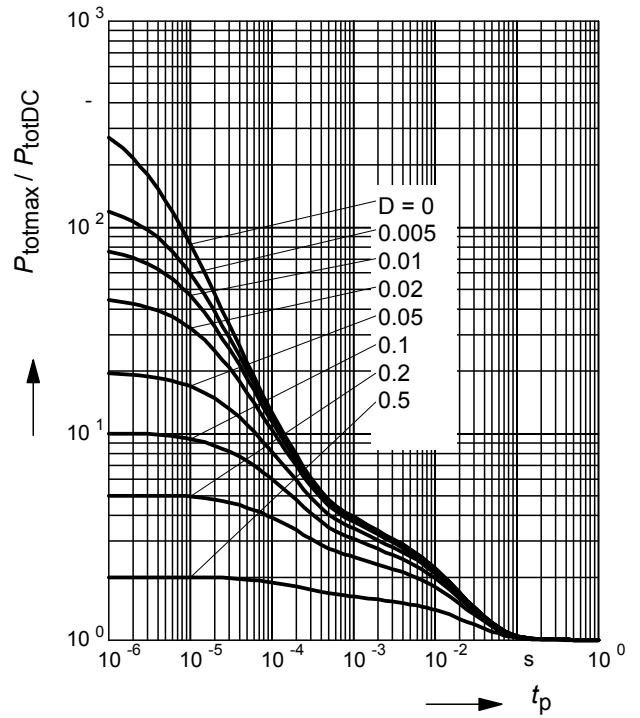
BCR133S



Permissible Pulse Load

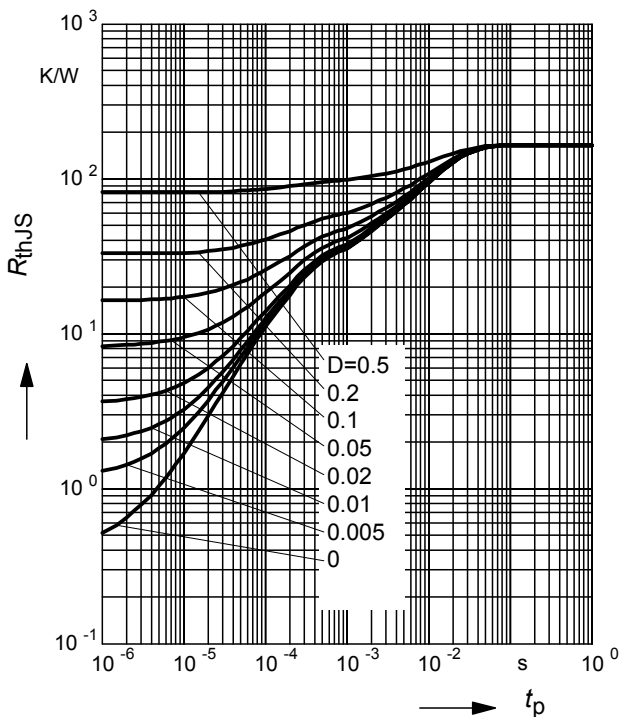
$P_{totmax}/P_{totDC} = f(t_p)$

BCR133S



Permissible Puls Load $R_{thJS} = f(t_p)$

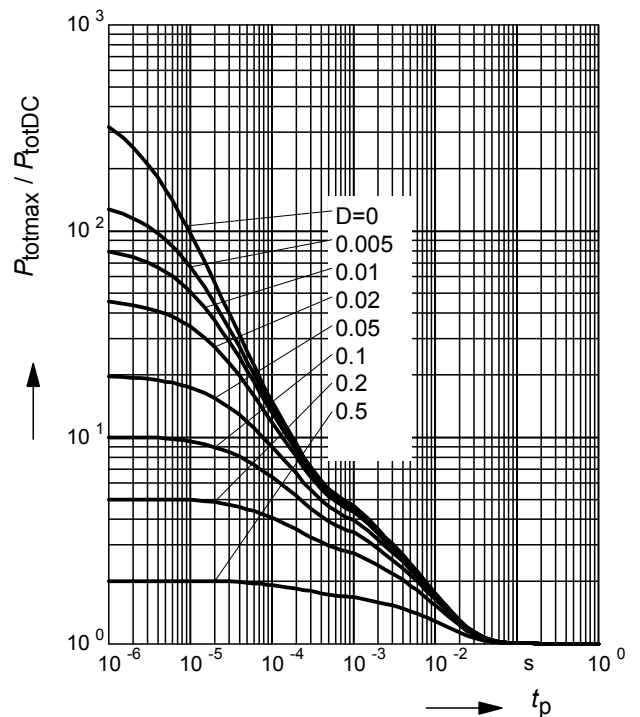
BCR133T



Permissible Pulse Load

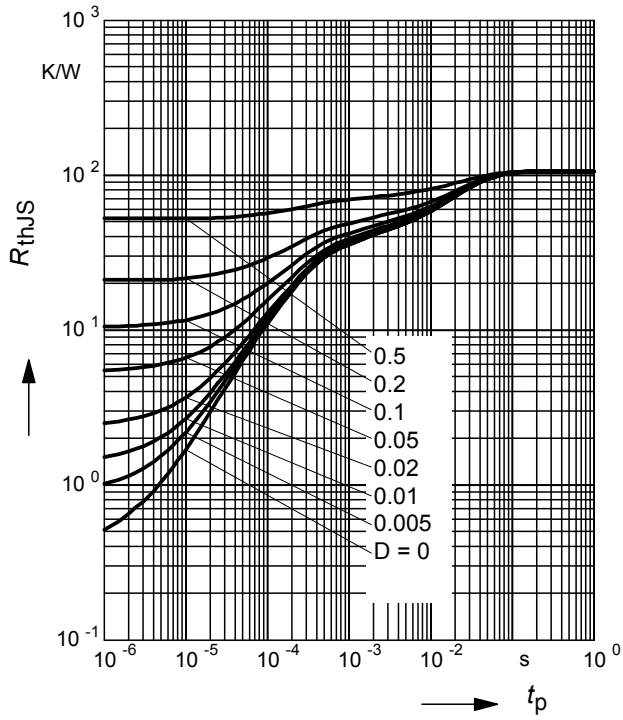
$P_{totmax}/P_{totDC} = f(t_p)$

BCR133T



Permissible Puls Load $R_{thJS} = f(t_p)$

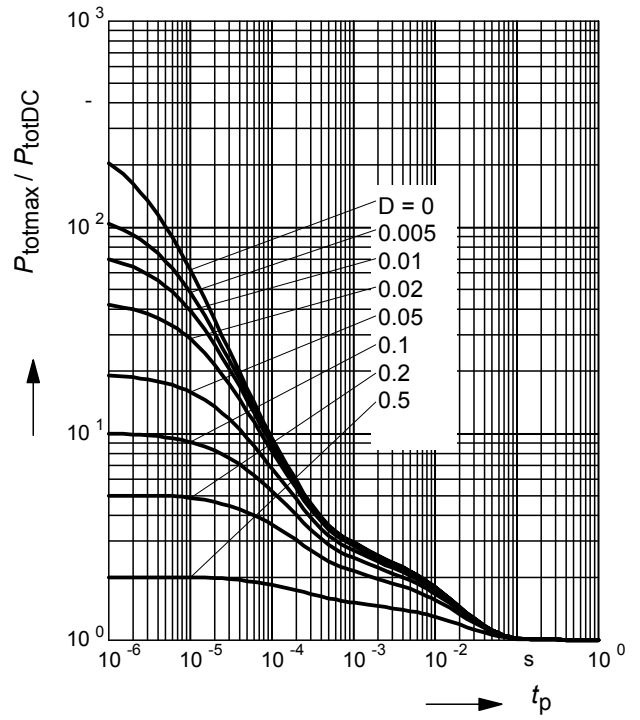
BCR133W



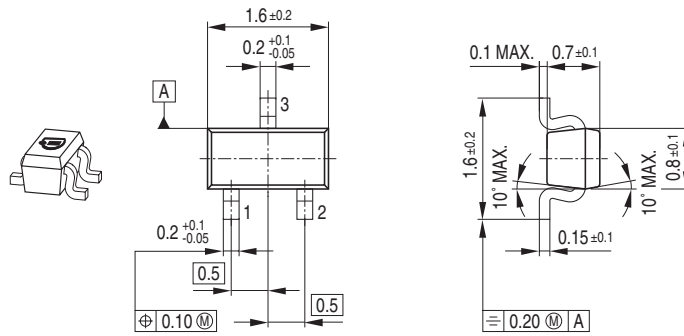
Permissible Pulse Load

$P_{totmax}/P_{totDC} = f(t_p)$

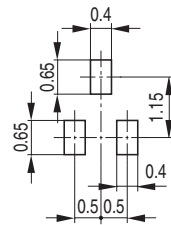
BCR133W



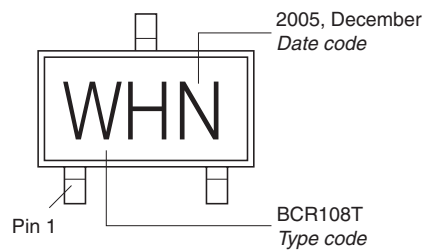
Package Outline



Foot Print

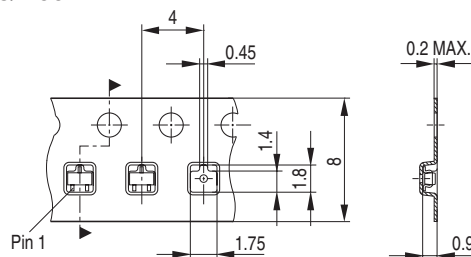


Marking Layout (Example)



Standard Packing

Reel $\phi 180$ mm = 3.000 Pieces/Reel
 Reel $\phi 330$ mm = 10.000 Pieces/Reel

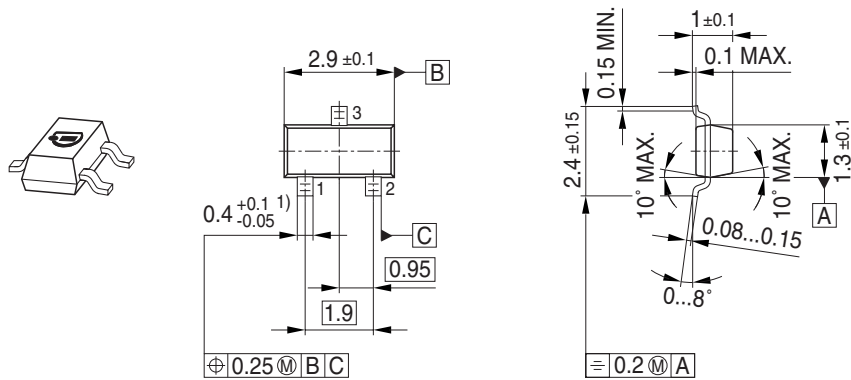


Date Code marking for discrete packages with one digit (SCD80, SC79, SC75¹⁾) CES-Code

Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

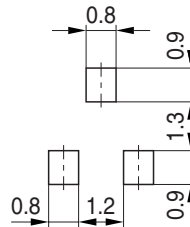
1) New Marking Layout for SC75, implemented at October 2005.

Package Outline

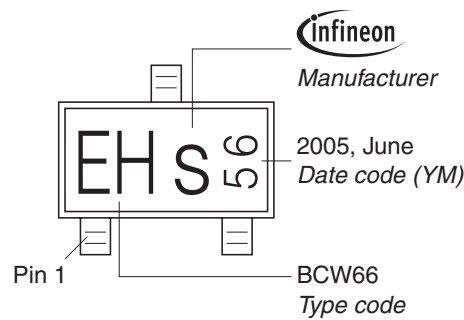


1) Lead width can be 0.6 max. in dambar area

Foot Print

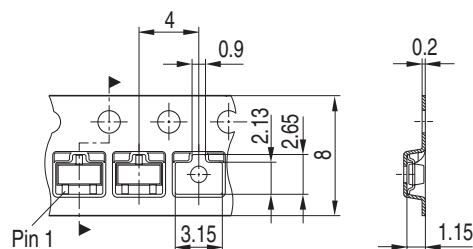


Marking Layout (Example)

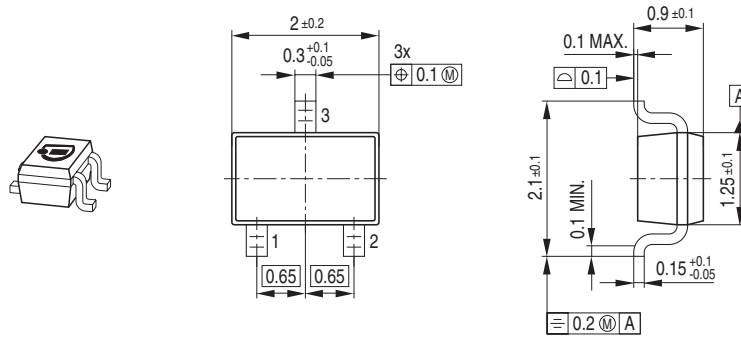


Standard Packing

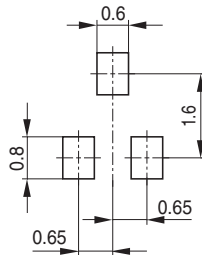
Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



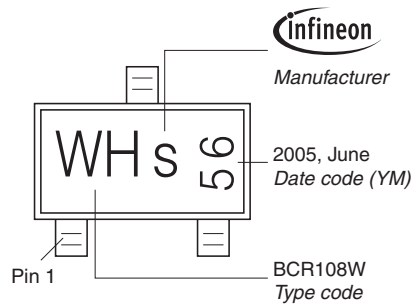
Package Outline



Foot Print

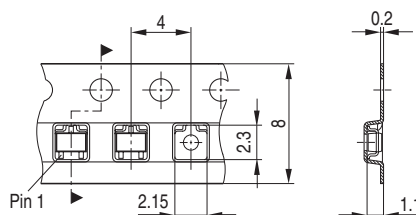


Marking Layout (Example)

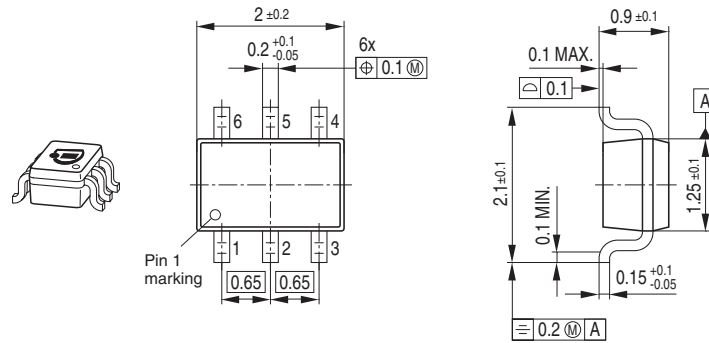


Standard Packing

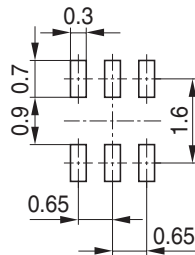
Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



Package Outline

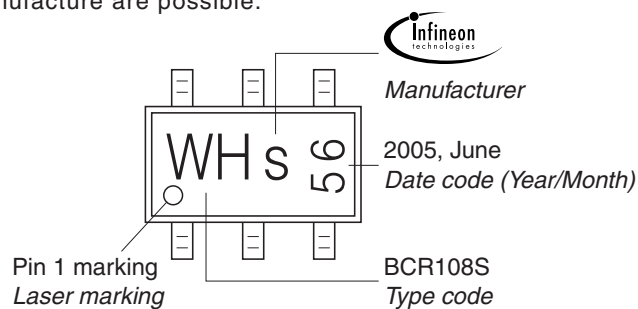


Foot Print



Marking Layout (Example)

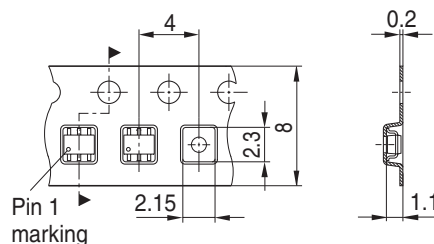
Small variations in positioning of Date code, Type code and Manufacture are possible.



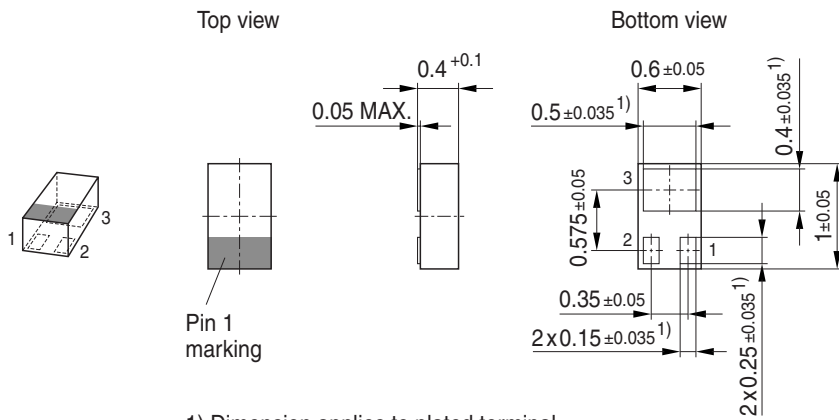
Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.

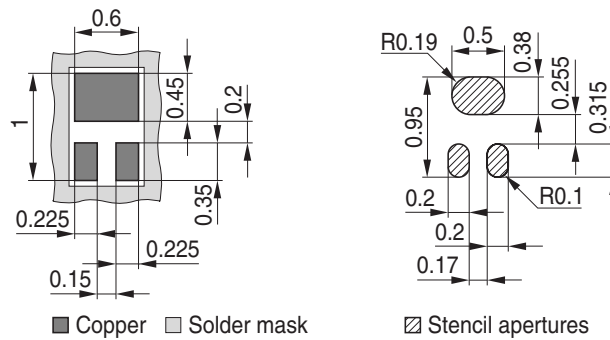


Package Outline

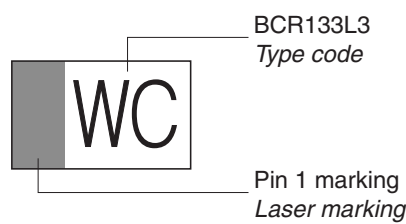


Foot Print

For board assembly information please refer to Infineon website "Packages"

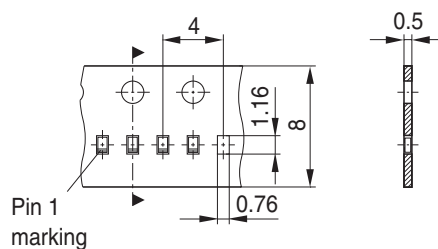


Marking Layout



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel



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www.s-manuals.com